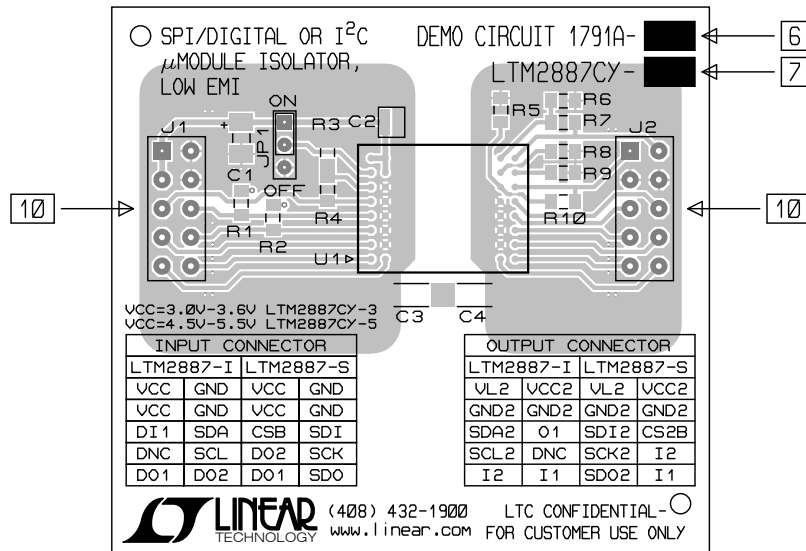


REVISION HISTORY

ECO	REV	DESCRIPTION	APPROVED	DATE
-	2	2ND PROTOTYPE	KEITH B.	3-4-15

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610
2. MAXIMUM SOLDER TEMPERATURE IS 250 DEGREES CELSIUS
3. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD
4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED
5. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD
6. MARK ASSEMBLY TYPE WITH BLACK PERMANENT MARKER WHERE SHOWN
7. MARK IC PART NUMBER WITH BLACK PERMANENT MARKER WHERE SHOWN
8. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD
9. INSTALL SHUNTS AS SHOWN
10. PLACE FERRITE BLOCK ON LONG SIDE HEADER PINS BEFORE BOARD INSERTION



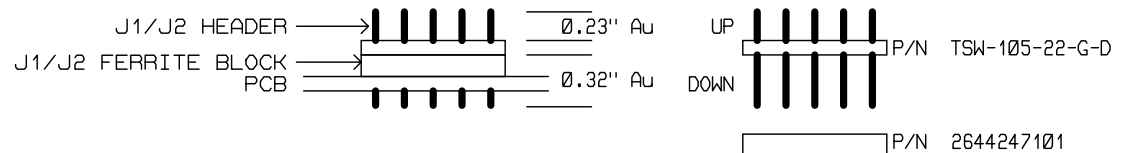
TOP SILKSCREEN LAYER

LINEAR TECHNOLOGY

DC1791A-2 * LTM2887CY-3S/-5S/-3I/-5I

SPI/DIGITAL OR I²C μMODULE ISOLATOR, LOW EMI

DATE: 3-4-15



ASSY	U1
-A	LTM2887CY-3S
-B	LTM2887CY-5S
-C	LTM2887CY-3I
-D	LTM2887CY-5I

APPROVALS				
PCB DES.	KEITH B.			
APP ENG.	KEITH B.			
		TITLE: ASSEMBLY DRAWING SPI/DIGITAL OR I ² C μMODULE ISOLATOR, LOW EMI		
		SIZE	IC NO.	REV.
		N/A	LTM2887CY-3S/-5S/-3I/-5I DEMO CIRCUIT 1791A	2
SCALE = 1.5:1		DATE: Wednesday March 4, 2015		SHEET 1 OF 1

1630 McCarthy Blvd.
Milpitas, CA 95035
Phone: (408) 432-1900
Fax: (408) 434-0507
www.linear.com

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